

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

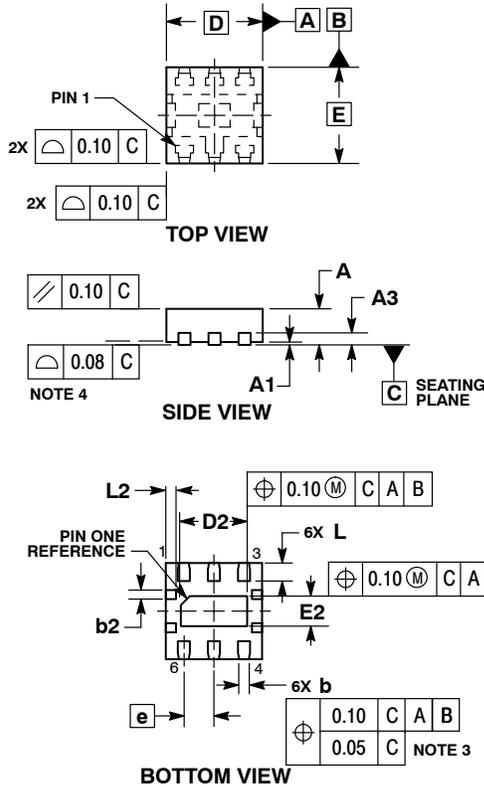
ON Semiconductor®



SCALE 2:1

CUDFN6 1.6x1.6, 0.5P  
CASE 505AL  
ISSUE A

DATE 09 FEB 2017



NOTES:

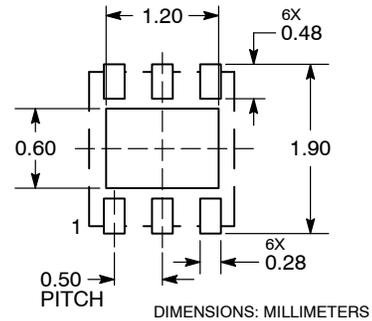
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
A3	0.20	REF
b	0.15	0.25
b2	0.15	REF
D	1.60	BSC
D2	1.05	1.15
E	1.60	BSC
E2	0.45	0.55
e	0.50	BSC
L	0.25	0.35
L2	0.17	REF

**GENERIC MARKING DIAGRAM\***

\*No marking due to clear package

**RECOMMENDED MOUNTING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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